

MicroThin™ Series

キャリア付き極薄銅箔

(アンテナ・モジュール用)
(ICサブストレート・マザーボード用)
(5G/6G・IoTサブストレート用)



MicroThin™

Thin copper foil for 5G/6G & IoT Substrate

MicroThin™ はハンドリング性と極薄性の両立を実現したMSAPに最適な銅箔です

MicroThin™ has a good handling ability as well as it is the ultra thin copper foil. MicroThin™ is the copper foil suitable for MSAP.

MicroThin™ Structure



MicroThin™ Line up

Variations		Surface roughness [μ m]	Target L/S by MSAP*	Thickness [μ m]			
				1.5	2	3	5
Standard	MT18SD-H	Rz 3.0	30/30 μ m	—	—	○	○
Low Profile	MT18Ex	Rz 2.0	25/25 μ m	○	○	○	○
Very Low Profile	MT18FL	Rz 1.3	15/15 μ m	○	○	○	—
Special Low Profile	MT18GN	Rz 0.9	10/10 μ m	○	○	○	—

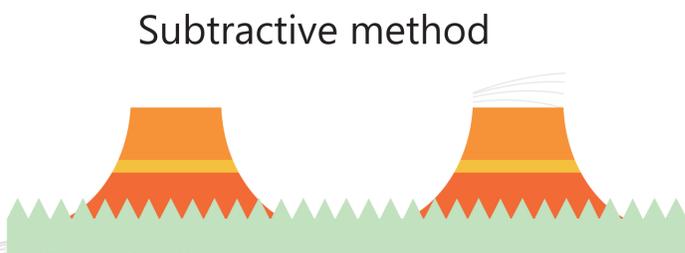
※MSAP: Modified Semi-Additive Process

Pattern shape

断面形状が矩形で且つ回路幅精度が高いMSAPは高周波用アンテナ回路に最適です

MSAP has a square shape and a high precision in a circuit width.

Therefore, MSAP is suitable for an antenna circuit for high frequencies.



Subtractive method



MSAP

MSAP Applications High-frequency antenna

Wireless communication



Quasi-millimeter-wave radar

LiDAR

Millimeter-wave radar

MSAP回路の特長

- ◎ 高い回路幅精度
- ◎ 低い電気抵抗
- ◎ 高い微細回路形成性

Feature of MSAP patterning

- ◎ High precision in a circuit width
- ◎ Low electric resistance
- ◎ High capability for fine patting



MITSUI
KINZOKU